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# **Dual Unbuffered Inverter**

The NL27WZU04 is a high performance dual unbuffered inverter operating from a 1.65 to 5.5 V supply. These devices are well suited for use as oscillators, pulse shapers, and in many other applications requiring a high-input impedance amplifier. For digital applications, the NL27WZ04 is recommended.

#### **Features**

- Designed for 1.65 V to 5.5 V V<sub>CC</sub> Operation
- Unbuffered for Crystal Oscillator and Analog Applications
- LVCMOS Compatible
- Source/Sink ±16 mA @ 4.5 V V<sub>CC</sub>
- Near Zero Static Supply Current Substantially Reduces System Power Requirements
- Chip Complexity: FET = 72; Equivalent Gate = 18
- These Devices are Pb-Free and are RoHS Compliant
- NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable

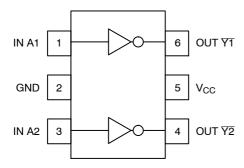


Figure 1. Pinout (Top View)

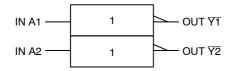


Figure 2. Logic Symbol



# ON Semiconductor®

http://onsemi.com

### MARKING DIAGRAMS



SC-88/SOT-363/SC-70 DF SUFFIX CASE 419B





TSOP-6 DT SUFFIX CASE 318G



M6 = Device Code
M = Date Code\*
• = Pb-Free Package

(Note: Microdot may be in either location)

\*Date Code orientation and/or position may vary depending upon manufacturing location.

#### **PIN ASSIGNMENT**

Pin	Function	
1	IN A1	
2	GND	
3	IN A2	
4	OUT Y2	
5	V <sub>CC</sub>	
6	OUT Y1	

#### **FUNCTION TABLE**

A Input	▼ Output
L	Н
Н	L

#### **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

#### **MAXIMUM RATINGS**

Symbol	Characteristics	Value	Units
V <sub>CC</sub>	DC Supply Voltage	-0.5 to +7.0	V
VI	DC Input Voltage	$-0.5 \le V_I \le V_{CC}$	V
Vo	DC Output Voltage	-0.5 to +7.0	V
I <sub>IK</sub>	DC Input Diode Current VI < GND	-50	mA
I <sub>OK</sub>	DC Output Diode Current $V_O < GND$ $V_O > V_{CC}$	-50 +50	mA
Io	DC Output Sink Current	±50	mA
I <sub>CC</sub>	DC Supply Current per Supply Pin	±100	mA
I <sub>GND</sub>	DC Ground Current per Ground Pin	±100	mA
T <sub>STG</sub>	Storage Temperature Range	-65 to +150	°C
P <sub>D</sub>	Power Dissipation in Still Air SC–88, TSOP–6	200	mW
$\theta_{\sf JA}$	Thermal Resistance SC–88, TSOP–6	333	°C/W
TL	Lead Temperature, 1 mm from Case for 10 s	260	°C
TJ	Junction Temperature under Bias	+150	°C
V <sub>ESD</sub>	ESD Withstand Voltage Human Body Model (Note 1) Machine Model (Note 2) Charged Device Model (Note 3)	> 2000 > 200 N/A	V
I <sub>Latchup</sub>	Latchup Performance Above V <sub>CC</sub> and Below GND at 85°C (Note 4)	±500	mA

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

- 1. Tested to EIA/JESD22-A114-A.
- 2. Tested to EIA/JESD22-A115-A.
- 3. Tested to JESD22-C101-A.
- 4. Tested to EIA/JESD78.

# RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Units
V <sub>CC</sub>	Supply Voltage Operating Data Retention Only	1.65 1.5	5.5 5.5	V
VI	Input Voltage	0	5.5	V
Vo	Output Voltage (High or LOW State)		5.5	V
T <sub>A</sub>	Operating Free–Air Temperature	-55	+125	°C
Δt/ΔV	Input Transition Rise or Fall Rate $V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$ $V_{CC} = 3.0 \text{ V} \pm 0.3 \text{ V}$ $V_{CC} = 5.0 \text{ V} \pm 0.5 \text{ V}$	0 0 0	20 10 5	ns/V

#### DC ELECTRICAL CHARACTERISTICS

	V <sub>CC</sub> T <sub>A</sub> = 25°C		C	-55°C ≤ T	<sub>A</sub> ≤ 125°C				
Symbol	Symbol Parameter Condi	Condition	(V)	Min	Тур	Max	Min	Max	Units
V <sub>IH</sub>	High-Level Input Voltage		1.65 to 1.85	0.85 V <sub>CC</sub>			0.85 V <sub>CC</sub>		V
			2.3 to 5.5	0.8 V <sub>CC</sub>			0.8 V <sub>CC</sub>		
V <sub>IL</sub>	Low-Level Input Voltage		1.65 to 1.85			0.15 V <sub>CC</sub>		0.15 V <sub>CC</sub>	V
			2.3 to 5.5			0.2 V <sub>CC</sub>		0.2 V <sub>CC</sub>	
V <sub>OH</sub>	High-Level Output Voltage V <sub>IN</sub> = V <sub>IL</sub>	I <sub>OH</sub> = -100 μA	1.65 to 5.5	V <sub>CC</sub> -0.1			V <sub>CC</sub> -0.1		V
	V <sub>IN</sub> = GND	I <sub>OH</sub> = -3 mA	1.65	1.29	1.52		1.29		
		I <sub>OH</sub> = -4 mA	2.3	1.9	2.1		1.9		
		I <sub>OH</sub> = -6 mA	2.7	2.2	2.3		2.2		
		I <sub>OH</sub> = -8 mA	3.0	2.4	2.6		2.4		
		I <sub>OH</sub> = -12 mA	3.0	2.3	2.5		2.3		
		I <sub>OH</sub> = -16 mA	4.5	3.8	4.2		3.8		
V <sub>OL</sub>	Low-Level Output Voltage V <sub>IN</sub> = V <sub>IH</sub>	I <sub>OL</sub> = 100 μA	1.65 to 5.5			0.1		0.1	V
	V <sub>IN</sub> = V <sub>CC</sub>	IOL = 3 mA	1.65		0.08	0.24		0.24	
		I <sub>OL</sub> = 4 mA	2.3		0.12	0.3		0.3	
		I <sub>OL</sub> = 6 mA	2.7		0.20	0.4		0.4	
		I <sub>OL</sub> = 8 mA	3.0		0.24	0.4		0.4	
		I <sub>OL</sub> = 12 mA	3.0		0.26	0.55		0.55	
		I <sub>OL</sub> = 16 mA	4.5		0.31	0.55		0.55	
I <sub>IN</sub>	Input Leakage Current	V <sub>IN</sub> = 5.5 V or GND	0 to 5.5			±0.1		±1.0	μΑ
l <sub>OFF</sub>	Power Off Leakage Current	V <sub>IN</sub> = 5.5 V or V <sub>OUT</sub> = 5.5 V	0			1		10	μА
I <sub>CC</sub>	Maximum Quiescent Supply Current	V <sub>IN</sub> = 5.5 V or GND	5.5			1.0		10	μΑ

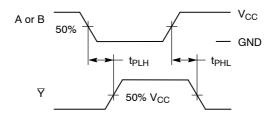
# AC ELECTRICAL CHARACTERISTICS $t_R$ = $t_F$ = 2.5 ns; $C_L$ = 50 pF; $R_L$ = 500 $\Omega$

				T <sub>A</sub> = 25°C		$-55^{\circ}\text{C} \le \text{T}_{\text{A}} \le 125^{\circ}\text{C}$			
Symbol	Parameter	Condition	V <sub>CC</sub> (V)	Min	Тур	Max	Min	Max	Units
t <sub>PLH</sub>	Propagation Delay	$R_L = 1 \text{ M}\Omega, C_L = 50 \text{ pF}$	1.8 ± 0.15	1.5	5.5	1.8	1.5	11.0	ns
t <sub>PHL</sub>	Input A to Y (Figure 3 and 4)	$R_L = 1 \text{ M}\Omega, C_L = 15 \text{ pF}$	2.5 ± 0.2	1.2	3.3	5.7	1.2	6.3	
		$R_L = 1 \text{ M}\Omega, C_L = 15 \text{ pF}$	$3.3\pm0.3$	0.8	2.7	4.1	0.8	4.5	
		$R_L = 500 \Omega$ , $C_L = 50 pF$		1.2	4.0	6.4	1.2	7.0	
		$R_L = 1 M\Omega$ , $C_L = 15 pF$	5.0 ± 0.5	0.5	2.2	3.3	0.5	3.6	
		$R_L = 500 \Omega, C_L = 50 pF$		0.8	3.4	5.6	0.8	6.2	

# **CAPACITIVE CHARACTERISTICS**

Symbol	Parameter	Condition	Typical	Units
C <sub>IN</sub>	Input Capacitance	$V_{CC} = 5.5 \text{ V}, V_{I} = 0 \text{ V or } V_{CC}$	7	pF
C <sub>OUT</sub>	Output Capacitance	V <sub>CC</sub> = 5.5 V, V <sub>I</sub> = 0 V or V <sub>CC</sub>	8	pF
C <sub>PD</sub>	Power Dissipation Capacitance (Note 5)	10 MHz, V <sub>CC</sub> = 5.5 V, V <sub>I</sub> = 0 V or V <sub>CC</sub>	25	pF

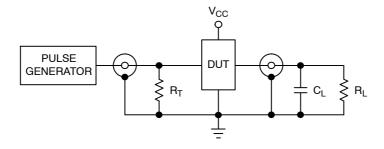
<sup>5.</sup> C<sub>PD</sub> is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation:  $I_{CC(OPR)} = C_{PD} \bullet V_{CC} \bullet f_{in} + I_{CC}$ .  $C_{PD}$  is used to determine the no–load dynamic power consumption;  $P_D = C_{PD} \bullet V_{CC}^2 \bullet f_{in} + I_{CC} \bullet V_{CC}$ .



#### **PROPAGATION DELAYS**

 $t_R = t_F = 2.5 \text{ ns}, 10\% \text{ to } 90\%; f = 1 \text{ MHz}; t_W = 500 \text{ ns}$ 

Figure 3. Switching Waveforms



 $C_L$  = 50 pF or equivalent (includes jig and probe capacitance)  $R_L$  =  $R_1$  = 500  $\Omega$  or equivalent  $R_T$  =  $Z_{OUT}$  of pulse generator (typically 50  $\Omega$ )

Figure 4. Test Circuit

# **ORDERING INFORMATION**

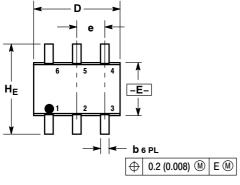
Device	Package	Shipping <sup>†</sup>
NL27WZU04DFT2G	SC-88 / SOT-363 / SC-70 (Pb-Free)	3000 / Tape & Reel
NLV27WZU04DFT2G*	SC-88 / SOT-363 / SC-70 (Pb-Free)	3000 / Tape & Reel
NL27WZU04DTT1G	TSOP-6 (Pb-Free)	3000 / Tape & Reel

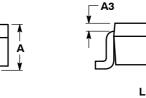
<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

<sup>\*</sup>NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable.

### PACKAGE DIMENSIONS

### SC-88/SC70-6/SOT-363 CASE 419B-02 **ISSUE W**



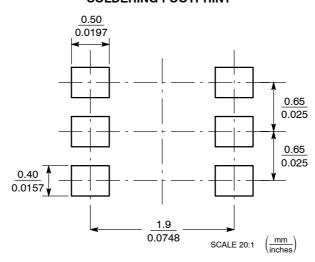


#### NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH. 3. 419B-01 OBSOLETE, NEW STANDARD 419B-02.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.80	0.95	1.10	0.031	0.037	0.043
A1	0.00	0.05	0.10	0.000	0.002	0.004
А3		0.20 RE	F	0.008 REF		
b	0.10	0.21	0.30	0.004	0.008	0.012
C	0.10	0.14	0.25	0.004	0.005	0.010
D	1.80	2.00	2.20	0.070	0.078	0.086
Е	1.15	1.25	1.35	0.045	0.049	0.053
е	0.65 BSC			0	.026 BS	С
L	0.10	0.20	0.30	0.004	0.008	0.012
HF	2.00	2.10	2.20	0.078	0.082	0.086

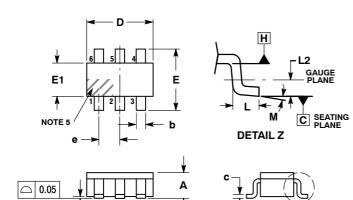
# **SOLDERING FOOTPRINT\***



<sup>\*</sup>For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

# **PACKAGE DIMENSIONS**

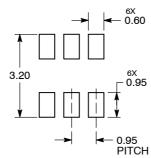
### TSOP-6 CASE 318G-02 **ISSUE U**



- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- CONTROLLING DIMENSION: MILLIMETERS.
  MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM
- LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
  DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH,
  PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.15 PER SIDE. DIMENSIONS D AND E1 ARE DETERMINED AT DATUM H. PIN ONE INDICATOR MUST BE LOCATED IN THE INDICATED ZONE.

	MILLIMETERS					
DIM	MIN	NOM	MAX			
Α	0.90	1.00	1.10			
A1	0.01	0.06	0.10			
b	0.25	0.38	0.50			
С	0.10	0.18	0.26			
D	2.90	3.00	3.10			
E	2.50	2.75	3.00			
E1	1.30	1.50 1.7				
е	0.85	0.95	1.05			
L	0.20	20 0.40 0.60				
L2	0.25 BSC					
M	0°	_	10°			

#### **RECOMMENDED SOLDERING FOOTPRINT\***



**DIMENSIONS: MILLIMETERS** 

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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